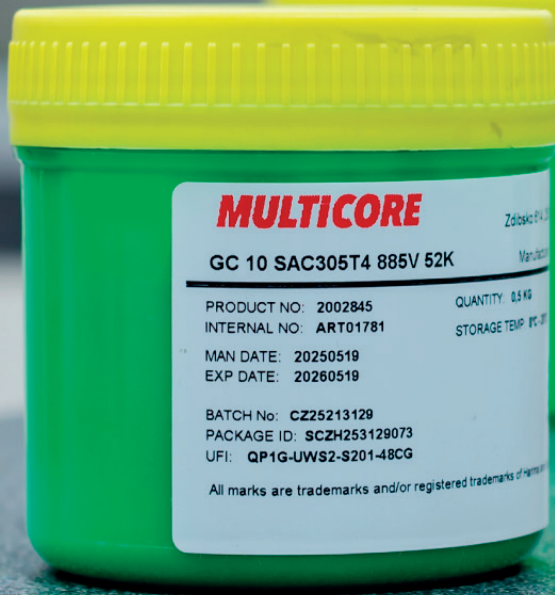




GC 10

solder paste



HARIMA MULTICORE GC 10

ROOM TEMPERATURE STABLE SOLDER PASTE

HARIMA MULTICORE GC 10 has been created as a reliable temperature stable solder paste providing stability at room temperature (26.5 °C) for one year and for one month at temperatures up to 40 °C.

This provides benefits for both logistics and operations from shipping and storage to printing and reflow. The temperature stability of this no-clean solder paste delivers exceptional performance with 24 hour abandon time, consistent stable paste transfer efficiency, a wide reflow process window in air, greater than 95 % on-line paste utilisation and a significant reduction in solder related defects. These advantages combine resulting in higher yields and cost effective PCB assembly.

TEMPERATURE STABLE

GC 10 BENEFITS

Improved printing	Improved stability	Improved reflow	Improved paste management
Six Sigma quality paste deposition with extended abandon times	On-line stencil stability of 3 days at 80 % RH	Excellent coalescence in air for 0201, 01005 and 0.3 mm pitch components	Exceptional on-line paste utilization
Groundbreaking standards for stencil life	At least 12x greater than conventional solder paste	Zero de-wetting in long soak, high temperature reflow profiles after 3 days at 80 % RH	End of day paste scrapping eliminated
High yield paste volumes with lowest aspect ratio: 20% lower than industry standard	Elevated temperature stability: x100 over conventional	Minimal hot slump at 182 °C, improving solder joint reliability	Eliminates requirement for refrigerated storage
Industry leader in paste transfer efficiency	Improved logistic management	Exceptional cosmetic appearance for lead-free solder joints	Eliminates requirement for cold or overnight shipment
Cost savings by reducing the amount of paste required	Wide process window	Flux technology improves total pad solderability in air with reduce paste volumes	Zero start up times and no kneading

GC 10 ATTRIBUTES AND BENEFITS

ATTRIBUTE		INDUSTRY STANDARD	GC 10	BENEFIT
FLUX	Regulatory compliance	Halide-free or halogen-free	Zero halogens added	✓
	IPC-J-STD-004B classification	ROLO	ROLO	
POWDER	Particle size distribution	Type 3, 4, 5	Type 3, 4, 5	
	Alloy	SAC305	SAC305	
STORAGE	Ambient (26.5 °C)	1 month	12 months	✓
	40 °C	1 day	1 month	✓
	50 °C	None	1 week	✓
PROCESS	On-line paste utilisation	75 %	> 95 %	✓
PRINTING	Abandon time	Up to 4 hours	Up to 24 hours	✓
	Stencil life	Up to 8 hours	Up to 12 hours	✓
	Startup time	4-24 hours	Immediate	✓
REFLOW	Soak temperature	150-180 °C	150-200 °C	✓
	Reflow atmosphere	Nitrogen	Air	✓

TEMPERATURE STABLE